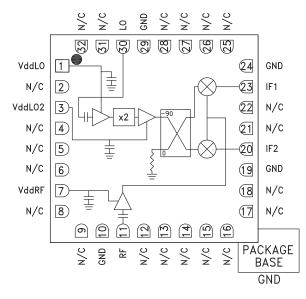


Typical Applications

The HMC572LC5 is ideal for:

- Point-to-Point and Point-to-Multi-Point Radio
- Military Radar, EW & ELINT
- Satellite Communications

Functional Diagram



HMC572LC5

GaAs MMIC I/Q DOWNCONVERTER 24 - 28 GHz

Features

8 dB Conversion Gain Image Rejection: 18 dB 2 LO to RF Isolation: 35 dB Noise Figure: 3.5 dB Input IP3: +5 dBm 32 Lead 5x5mm SMT Package: 25mm²

General Description

The HMC572LC5 is a compact GaAs MMIC I/Q downconverter in a leadless RoHS compliant SMT package. This device provides a small signal conversion gain of 8 dB with a noise figure of 3.5 dB and 18 dB of image rejection across the frequency band. The HMC572LC5 utilizes an LNA followed by an image reject mixer which is driven by an active x2 multiplier. The image reject mixer eliminates the need for a filter following the LNA, and removes thermal noise at the image frequency. I and Q mixer outputs are provided and an external 90° hybrid is needed to select the required sideband. The HMC572LC5 is a much smaller alternative to hybrid style image reject mixer downconverter assemblies, and it eliminates the need for wire bonding by allowing the use of surface mount manufacturing techniques.

Units Parameter Min. Max. Min. Max Тур. Тур. 23 - 28 Frequency Range, RF 24.5 - 26.5 GHz 9 - 15.5 9 - 15.5 GHz Frequency Range, LO Frequency Range, IF DC - 3.5 DC - 3.5 GHz Conversion Gain (As IRM) 8.0 dB 6.0 6 10 Noise Figure 3.5 3.5 dB dB Image Rejection 14 17 14 20 -7 1 dB Compression (Input) -6 -4 -5 dBm 2 LO to RF Isolation 32 dB 35 30 35 2 LO to IF Isolation 30 40 25 40 dB IP3 (Input) +5 +8 +6 dBm +3 Amplitude Balance dB 0.3 0.4 Phase Balance 5 8 Deg 165 **Total Supply Current** 125 125 165 mΑ *Data taken as IRM with external IF Hybrid

Electrical Specifications, $T_A = +25^{\circ}$ C, IF = 100 MHz, LO = +4 dBm, Vdd = 3.5 Vdc*

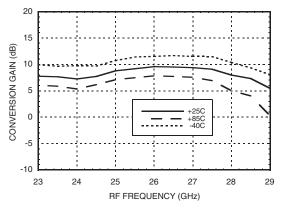
24 - 28 GHz



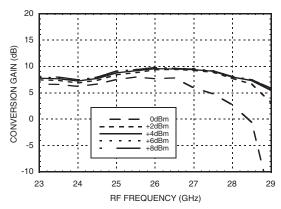
ROHS V

Data Taken As IRM With External IF Hybrid

Conversion Gain vs. Temperature



Conversion Gain vs. LO Drive



Input P1dB vs. Temperature

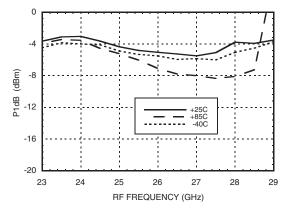
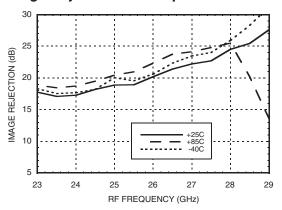
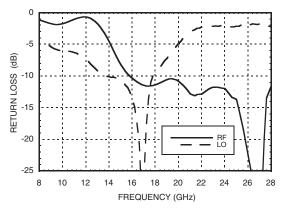


Image Rejection vs. Temperature

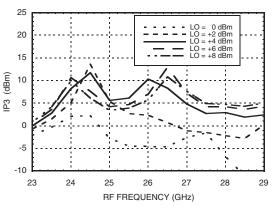
GaAs MMIC I/Q DOWNCONVERTER



Return Loss



Input IP3 vs. LO Drive



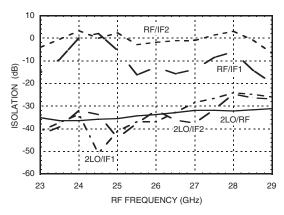


GaAs MMIC I/Q DOWNCONVERTER 24 - 28 GHz

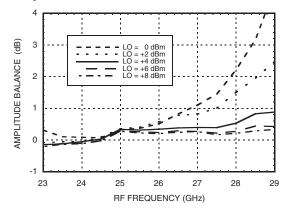


Quadrature Channel Data Taken Without IF Hybrid

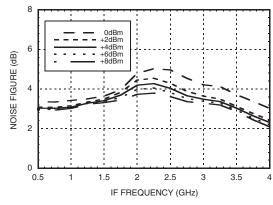
Isolations

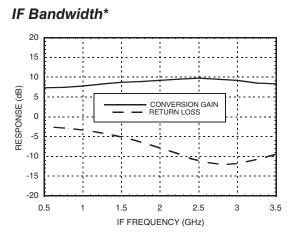


Amplitude Balance vs. LO Drive

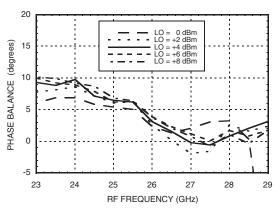


Noise Figure vs. LO Drive, LO Frequency = 12 GHz

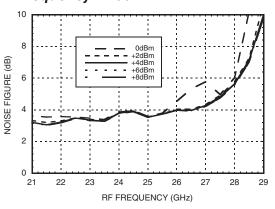




Phase Balance vs. LO Drive



Noise Figure vs. LO Drive, IF Frequency = 100 MHz



* Conversion gain data taken with external IF hybrid, LO frequency fixed at 12 GHz and RF varied





GaAs MMIC I/Q DOWNCONVERTER 24 - 28 GHz

MxN Spurious Outputs

	nLO				
mRF	0	1	2	3	4
0	xx	37	12	32	45
1	12	41	0	37	41
2	xx	хх	66	70	46
3	xx	хх	xx	хх	79
4	xx	хх	xx	хх	xx
RF = 25 GHz @ -20 dBm					
LO = 12 GHz @ +4 dBm					
Data taken without IF hybrid					
All values in dBc below IF power level (1RF -2LO = 1 GHz)					

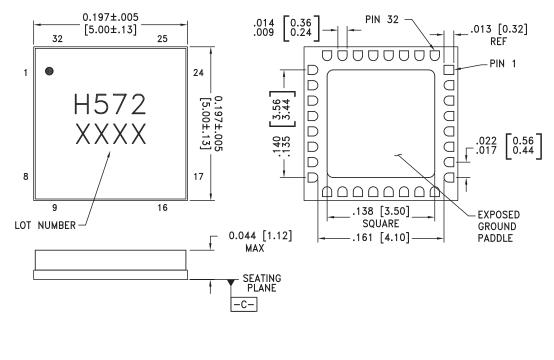
Absolute Maximum Ratings

RF	+2 dBm	
LO Drive	+ 13 dBm	
Vdd	5.5V	
Channel Temperature	175°C	
Continuous Pdiss (T=85°C) (derate 9.56 mW/°C above 85°C)	860 mW	
Thermal Resistance (R _{TH}) (channel to package bottom)	104.6 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-55 to +85 °C	
ESD Sensitivity (HBM)	Class 1B	



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS





BOTTOM VIEW

NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING: 30 80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKLE
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND

For price, delivery, and to place orders, please contact Hittite Microwave Corporation: 20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373 8



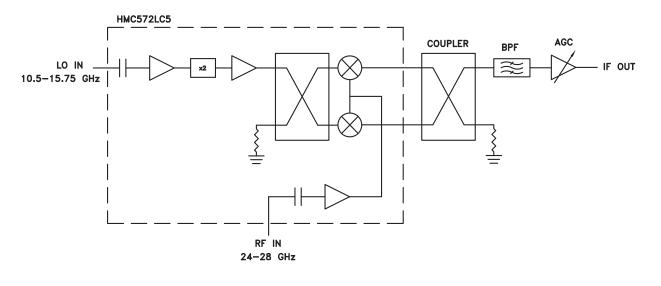
RoHS EARTH FRIENDL

GaAs MMIC I/Q DOWNCONVERTER 24 - 28 GHz

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	VddLO	Power supply for first stage of LO amplifier.	VddLO O
2, 4 - 6, 8, 9, 12 - 18, 21, 22, 25 - 28, 31, 32	N/C	No connection required. These pins may be connected to RF/DC ground without affecting performance.	
3	VddLO2	Power supply for second stage of LO amplifier.	VddL02 O
7	VddRF	Power supply for RF LNA.	VddRF O
10, 19, 24, 29	GND	These pins and ground paddle must be connected to RF/DC ground.	
11	RF	This pin is AC coupled and matched to 50 Ohms.	RF ○
20	IF2	This pin is DC coupled for applications not requir- ing operation to DC. This port should be DC blocked externally using a series capacitor whose value has	IF1,IF2
23	IF1	been chosen to pass the necessary frequency range. For operation to DC, this pin must not sink / source more than 3 mA of current or part non-function and possible failure will result.	
30	LO	This pin is AC coupled and matched to 50 Ohms.	

Typical Application

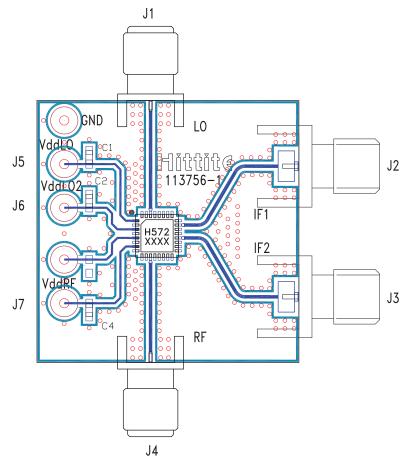




GaAs MMIC I/Q DOWNCONVERTER 24 - 28 GHz



Evaluation PCB



List of Materials for Evaluation PCB 113758 [1]

Item	Description
C1 - C4	Capacitor 0603, 0.01 µF
J1, J4	PCB Mount SMA RF Connector, SRI
J2, J3	PCB Mount SMA Connector, Johnson
J5 - J7	DC Pin
U1	HMC572LC5
PCB [2]	113756 Evaluation Board

Reference this number when ordering complete evaluation PCB
Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.